

ABSTRACT

WAFER PROCESSING METHOD

Disclosed herein is a wafer processing method for processing a wafer including a substrate and a functional layer formed on the front side of the substrate. The wafer processing method includes a protective tape attaching step, a cut groove forming step, and a dividing step. The protective tape attaching step is the step of attaching a protective tape curable by an external stimulation to the front side of the functional layer. The cut groove forming step is the step of cutting the substrate from the back side thereof along each division line by using a cutting blade, thereby forming a cut groove having a depth not reaching the functional layer with a part of the substrate left between the bottom of the cut groove and the functional layer. The dividing step is the step of applying a laser beam having an absorption wavelength to the substrate along the cut groove, thereby dividing the remaining part of the substrate to divide the wafer into device chips. In the cut groove forming step, an uncut portion in which the cut groove is not formed is left in a peripheral marginal area of the wafer.

(Figure 16)